

Zhongxu Wang

List of Publications by Year in descending order

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times ranked

378
citing authors

#	ARTICLE	IF	CITATIONS
1	A Guideline for Reliability Prediction in Power Electronic Converters. IEEE Transactions on Power Electronics, 2020, 35, 10958-10968.	7.9	91
2	Simplified Thermal Modeling for IGBT Modules With Periodic Power Loss Profiles in Modular Multilevel Converters. IEEE Transactions on Industrial Electronics, 2019, 66, 2323-2332.	7.9	85
3	Mission Profile-Based System-Level Reliability Prediction Method for Modular Multilevel Converters. IEEE Transactions on Power Electronics, 2020, 35, 6916-6930.	7.9	50
4	Impact of lifetime model selections on the reliability prediction of IGBT modules in modular multilevel converters. , 2017, , .		44
5	Condition Monitoring for Submodule Capacitors in Modular Multilevel Converters. IEEE Transactions on Power Electronics, 2019, 34, 10403-10407.	7.9	38
6	Capacitor Condition Monitoring Based on the DC-Side Start-Up of Modular Multilevel Converters. IEEE Transactions on Power Electronics, 2020, 35, 5589-5593.	7.9	33
7	Reliability Modeling of Power Electronic Converters: A General Approach. , 2019, , .		29
8	Artificial Intelligence-Aided Thermal Model Considering Cross-Coupling Effects. IEEE Transactions on Power Electronics, 2020, 35, 9998-10002.	7.9	29
9	A Reference Submodule Based Capacitor Condition Monitoring Method for Modular Multilevel Converters. IEEE Transactions on Power Electronics, 2020, 35, 6691-6696.	7.9	25
10	A Viable Mission Profile Emulator for Power Modules in Modular Multilevel Converters. IEEE Transactions on Power Electronics, 2019, 34, 11580-11593.	7.9	17
11	Simplified Multi-time Scale Thermal Model Considering Thermal Coupling in IGBT Modules. , 2019, , .		16
12	The impact of mission profile models on the predicted lifetime of IGBT modules in the modular multilevel converter. , 2017, , .		14
13	A Simplification Method for Power Device Thermal Modeling With Quantitative Error Analysis. IEEE Journal of Emerging and Selected Topics in Power Electronics, 2019, 7, 1649-1658.	5.4	14
14	Computational-Efficient Thermal Estimation for IGBT Modules Under Periodic Power Loss Profiles in Modular Multilevel Converters. IEEE Transactions on Industry Applications, 2019, 55, 4984-4992.	4.9	13
15	Balanced Conduction Loss Distribution among SMs in Modular Multilevel Converters. , 2018, , .		11
16	Submodule Level Power Loss Balancing Control for Modular Multilevel Converters. , 2018, , .		11
17	An analytical essential switching loss estimation method for modular multilevel converters with nearest level modulation. , 2017, , .		5
18	System-Level Power Loss Evaluation of Modular Multilevel Converters. , 2019, , .		4

#	ARTICLE	IF	CITATIONS
19	System-Level Thermal Modeling of a Modular Multilevel Converter. , 2020, , .		4
20	Impact of the Thermal-Interface-Material Thickness on IGBT Module Reliability in the Modular Multilevel Converter. , 2018, , .		3
21	Condition Monitoring Method for Submodule Capacitor in Modular Multilevel Converter. , 2019, , .		3
22	Simplified Estimation of the Junction Temperature Fluctuation at the Output Frequency for IGBT Modules in Modular Multilevel Converters. , 2018, , .		2
23	Mission Profile Based Adaptive Carrier Frequency Control for Modular Multilevel Converters for Medium Voltage Applications. , 2019, , .		0